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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	M8C
Core Size	8-Bit
Speed	24MHz
Connectivity	I²C, SPI, UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	28
Program Memory Size	8KB (8K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.25V
Data Converters	A/D 28x8b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	32-VFQFN Exposed Pad
Supplier Device Package	32-QFN (5x5)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/cy8c21634-24ltxit

PSoC Functional Overview

The PSoC family consists of many devices with on-chip controllers. These devices are designed to replace multiple traditional MCU-based system components with one low-cost single-chip programmable component. A PSoC device includes configurable blocks of analog and digital logic, and programmable interconnect. This architecture makes it possible for you to create customized peripheral configurations, to match the requirements of each individual application. Additionally, a fast central processing unit (CPU), flash program memory, SRAM data memory, and configurable I/O are included in a range of convenient pinouts.

The PSoC architecture, shown in Figure 2, consists of four main areas: the core, the system resources, the digital system, and the analog system. Configurable global bus resources allow combining all of the device resources into a complete custom system. Each CY8C21x34 PSoC device includes four digital blocks and four analog blocks. Depending on the PSoC package, up to 28 GPIOs are also included. The GPIOs provide access to the global digital and analog interconnects.

The PSoC Core

The PSoC core is a powerful engine that supports a rich instruction set. It encompasses SRAM for data storage, an interrupt controller, sleep and watchdog timers, and internal main oscillator (IMO) and internal low speed oscillator (ILO). The CPU core, called the M8C, is a powerful processor with speeds up to 24 MHz [3]. The M8C is a four-million instructions per second (MIPS) 8-bit Harvard-architecture microprocessor.

System resources provide these additional capabilities:

- Digital clocks for increased flexibility
- I^2C [4] functionality to implement an I^2C master and slave
- An internal voltage reference, multi-master, that provides an absolute value of 1.3 V to a number of PSoC subsystems
- A SMP that generates normal operating voltages from a single battery cell
- Various system resets supported by the M8C

The digital system consists of an array of digital PSoC blocks that may be configured into any number of digital peripherals. The digital blocks are connected to the GPIOs through a series of global buses. These buses can route any signal to any pin, freeing designs from the constraints of a fixed peripheral controller.

The analog system consists of four analog PSoC blocks, supporting comparators, and analog-to-digital conversion up to 10 bits of precision.

The Digital System

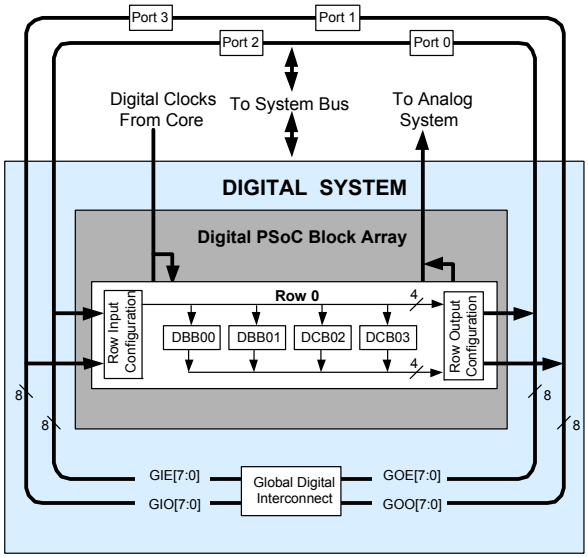
The digital system consists of four digital PSoC blocks. Each block is an 8-bit resource that is used alone or combined with other blocks to form 8-, 16-, 24-, and 32-bit peripherals, which are called user modules. Digital peripheral configurations include:

- PWMs (8- to 32-bit)
- PWMs with dead band (8- to 32-bit)
- Counters (8- to 32-bit)
- Timers (8- to 32-bit)
- UART 8- with selectable parity
- Serial peripheral interface (SPI) master and slave
- I^2C slave and multi-master [4]
- CRC/generator (8-bit)
- IrDA
- PRS generators (8-bit to 32-bit)

The digital blocks are connected to any GPIO through a series of global buses that can route any signal to any pin. The buses also allow for signal multiplexing and for performing logic operations. This configurability frees your designs from the constraints of a fixed peripheral controller.

Digital blocks are provided in rows of four, where the number of blocks varies by PSoC device family. This allows the optimum choice of system resources for your application. Family resources are shown in Table 1 on page 6.

Figure 2. Digital System Block Diagram



Notes
3. Errata: The worst case IMO frequency deviation when operated below 0 °C and above +70 °C and within the upper and lower datasheet temperature range is ±5%.
4. Errata:The I^2C block exhibits occasional data and bus corruption errors when the I^2C master initiates transactions while the device is transitioning in to or out of sleep mode.

Designing with PSoC Designer

The development process for the PSoC device differs from that of a traditional fixed function microprocessor. The configurable analog and digital hardware blocks give the PSoC architecture a unique flexibility that pays dividends in managing specification change during development and by lowering inventory costs. These configurable resources, called PSoC Blocks, have the ability to implement a wide variety of user-selectable functions. The PSoC development process is summarized in four steps:

1. Select User Modules.
2. Configure User Modules.
3. Organize and Connect.
4. Generate, Verify, and Debug.

Select User Modules

PSoC Designer provides a library of prebuilt, pretested hardware peripheral components called “user modules.” User modules make selecting and implementing peripheral devices, both analog and digital, simple.

Configure User Modules

Each user module that you select establishes the basic register settings that implement the selected function. They also provide parameters and properties that allow you to tailor their precise configuration to your particular application. For example, a PWM User Module configures one or more digital PSoC blocks, one for each 8 bits of resolution. The user module parameters permit you to establish the pulse width and duty cycle. Configure the parameters and properties to correspond to your chosen application. Enter values directly or by selecting values from drop-down menus. All the user modules are documented in datasheets that may be viewed directly in PSoC Designer or on the Cypress website. These user module datasheets explain the internal operation of the user module and provide performance specifications. Each datasheet describes the use of each user module parameter, and other information you may need to successfully implement your design.

Organize and Connect

You build signal chains at the chip level by interconnecting user modules to each other and the I/O pins. You perform the selection, configuration, and routing so that you have complete control over all on-chip resources.

Generate, Verify, and Debug

When you are ready to test the hardware configuration or move on to developing code for the project, you perform the “Generate Configuration Files” step. This causes PSoC Designer to generate source code that automatically configures the device to your specification and provides the software for the system. The generated code provides application programming interfaces (APIs) with high-level functions to control and respond to hardware events at run-time and interrupt service routines that you can adapt as needed.

A complete code development environment allows you to develop and customize your applications in either C, assembly language, or both.

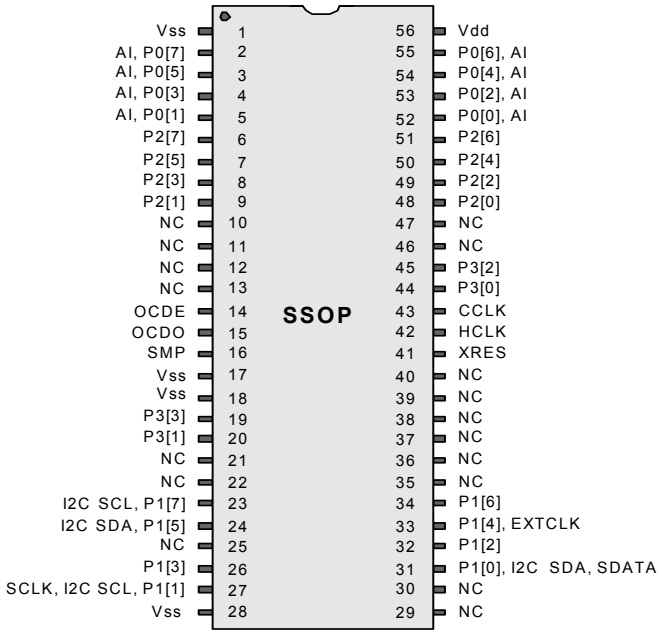
The last step in the development process takes place inside PSoC Designer’s debugger (access by clicking the Connect icon). PSoC Designer downloads the HEX image to the ICE where it runs at full speed. PSoC Designer debugging capabilities rival those of systems costing many times more. In addition to traditional single-step, run-to-breakpoint, and watch-variable features, the debug interface provides a large trace buffer and allows you to define complex breakpoint events. These include monitoring address and data bus values, memory locations, and external signals.

56-pin Part Pinout

The 56-pin SSOP part is for the CY8C21001 on-chip debug (OCD) PSoC device.

Note This part is only used for in-circuit debugging. It is NOT available for production.

Figure 10. CY8C21001 56-pin PSoC Device



CY8C21001 56-pin SSOP Pin Definitions

Pin No.	Type		Pin Name	Description
	Digital	Analog		
1	Power		V_{SS}	Ground connection [18]
2	I/O	I	P0[7]	Analog column mux input
3	I/O	I	P0[5]	Analog column mux input and column output
4	I/O	I	P0[3]	Analog column mux input and column output
5	I/O	I	P0[1]	Analog column mux input
6	I/O		P2[7]	
7	I/O		P2[5]	
8	I/O	I	P2[3]	Direct switched capacitor block input
9	I/O	I	P2[1]	Direct switched capacitor block input
10			NC	No connection. Pin must be left floating
11			NC	No connection. Pin must be left floating
12			NC	No connection. Pin must be left floating
13			NC	No connection. Pin must be left floating
14	OCD		OCDE	OCD even data I/O
15	OCD		OCDO	OCD odd data output
16	Power		SMP	SMP connection to required external components
17	Power		V_{SS}	Ground connection [18]
18	Power		V_{SS}	Ground connection [18]
19	I/O		P3[3]	

CY8C21001 56-pin SSOP Pin Definitions (continued)

Pin No.	Type		Pin Name	Description
	Digital	Analog		
20	I/O		P3[1]	
21			NC	No connection. Pin must be left floating
22			NC	No connection. Pin must be left floating
23	I/O		P1[7]	I^2C SCL
24	I/O		P1[5]	I^2C SDA
25			NC	No connection. Pin must be left floating
26	I/O		P1[3]	I_{FMTEST}
27	I/O		P1[1]	I^2C SCL, ISSP-SCLK[19]
28	Power		V_{SS}	Ground connection [18]
29			NC	No connection. Pin must be left floating
30			NC	No connection. Pin must be left floating
31	I/O		P1[0]	I^2C SDA, ISSP-SDATA[19]
32	I/O		P1[2]	V_{FMTEST}
33	I/O		P1[4]	Optional external clock input (EXTCLK)
34	I/O		P1[6]	
35			NC	No connection. Pin must be left floating
36			NC	No connection. Pin must be left floating
37			NC	No connection. Pin must be left floating
38			NC	No connection. Pin must be left floating
39			NC	No connection. Pin must be left floating
40			NC	No connection. Pin must be left floating
41	Input		XRES	Active high external reset with internal pull-down
42	OCD		HCLK	OCD high-speed clock output
43	OCD		CCLK	OCD CPU clock output
44	I/O		P3[0]	
45	I/O		P3[2]	
46			NC	No connection. Pin must be left floating
47			NC	No connection. Pin must be left floating
48	I/O	I	P2[0]	
49	I/O	I	P2[2]	
50	I/O		P2[4]	
51	I/O		P2[6]	
52	I/O	I	P0[0]	Analog column mux input
53	I/O	I	P0[2]	Analog column mux input and column output
54	I/O	I	P0[4]	Analog column mux input and column output
55	I/O	I	P0[6]	Analog column mux input
56	Power		V_{DD}	Supply voltage

LEGEND: A = Analog, I = Input, O = Output, and OCD = On-Chip Debug.

Notes
18. All V_{SS} pins should be brought out to one common GND plane.
19. These are the ISSP pins, which are not High Z at POR. See the *PSoC Technical Reference Manual* for details.

DC Switch Mode Pump Specifications

Table 11 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Figure 12. Basic Switch Mode Pump Circuit

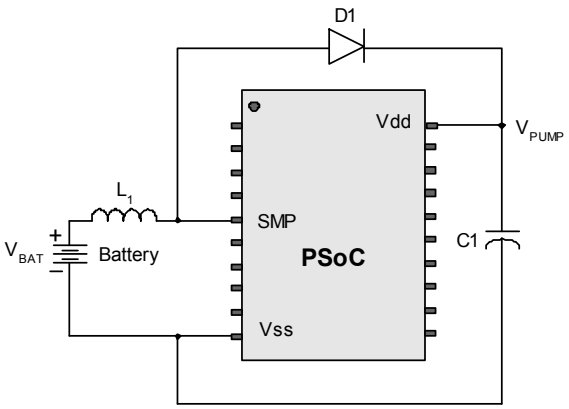


Table 11. DC Switch Mode Pump (SMP) Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{PUMP5V}	5 V output voltage from pump	4.75	5.0	5.25	V	Configured as in Note 20 Average, neglecting ripple SMP trip voltage is set to 5.0 V
V_{PUMP3V}	3.3 V output voltage from pump	3.00	3.25	3.60	V	Configured as in Note 20 Average, neglecting ripple. SMP trip voltage is set to 3.25 V
V_{PUMP2V}	2.6 V output voltage from pump	2.45	2.55	2.80	V	Configured as in Note 20 Average, neglecting ripple. SMP trip voltage is set to 2.55 V
I_{PUMP}	Available output current V_{BAT} = 1.8 V, V_{PUMP} = 5.0 V V_{BAT} = 1.5 V, V_{PUMP} = 3.25 V V_{BAT} = 1.3 V, V_{PUMP} = 2.55 V	 5 8 8	 – – –	 – – –	 mA mA mA	Configured as in Note 20 SMP trip voltage is set to 5.0 V SMP trip voltage is set to 3.25 V SMP trip voltage is set to 2.55 V
V_{BAT5V}	Input voltage range from battery	1.8	–	5.0	V	Configured as in Note 20 SMP trip voltage is set to 5.0 V
V_{BAT3V}	Input voltage range from battery	1.0	–	3.3	V	Configured as in Note 20 SMP trip voltage is set to 3.25 V
V_{BAT2V}	Input voltage range from battery	1.0	–	2.8	V	Configured as in Note 20 SMP trip voltage is set to 2.55 V
$V_{BATSTART}$	Minimum input voltage from battery to start pump	1.2	–	–	V	Configured as in Note 20 0 °C ≤ T_A ≤ 100. 1.25 V at T_A = –40 °C
ΔV_{PUMP_Line}	Line regulation (over Vi range)	–	5	–	$\%V_O$	Configured as in Note 20 V_O is the "V_{DD} Value for PUMP Trip" specified by the VM[2:0] setting in the DC POR and LVD Specification, Table 13 on page 24
ΔV_{PUMP_Load}	Load regulation	–	5	–	$\%V_O$	Configured as in Note 20 V_O is the "V_{DD} Value for PUMP Trip" specified by the VM[2:0] setting in the DC POR and LVD Specification, Table 13 on page 24
ΔV_{PUMP_Ripple}	Output voltage ripple (depends on cap/load)	–	100	–	mVpp	Configured as in Note 20 Load is 5 mA
E_3	Efficiency	35	50	–	%	Configured as in Note 20 Load is 5 mA. SMP trip voltage is set to 3.25 V

Note
20. L_1 = 2 mH inductor, C_1 = 10 mF capacitor, D_1 = Schottky diode. See Figure 12 on page 23.

Table 11. DC Switch Mode Pump (SMP) Specifications (continued)

Symbol	Description	Min	Typ	Max	Units	Notes
E_2	Efficiency	35	80	–	%	For I load = 1mA, V_{PUMP} = 2.55 V, V_{BAT} = 1.3 V, 10 µH inductor, 1 µF capacitor, and Schottky diode
F_{PUMP}	Switching frequency	–	1.3	–	MHz	
DC_{PUMP}	Switching duty cycle	–	50	–	%	

DC Analog Mux Bus Specifications

Table 12 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 12. DC Analog Mux Bus Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
R_{SW}	Switch resistance to common analog bus	–	–	400 800	Ω	V_{DD} ≥ 2.7 V 2.4 V ≤ V_{DD} ≤ 2.7 V
R_{VDD}	Resistance of initialization switch to V_{DD}	–	–	800	Ω	

DC POR and LVD Specifications

Table 13 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 13. DC POR and LVD Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
	V_{DD} value for PPOR trip					V_{DD} must be greater than or equal to 2.5 V during startup, the reset from the XRES pin, or reset from watchdog
V_{PPOR0}	PORLEV[1:0] = 00b	–	2.36	2.40	V	
V_{PPOR1}	PORLEV[1:0] = 01b	–	2.82	2.95	V	
V_{PPOR2}	PORLEV[1:0] = 10b	–	4.55	4.70	V	
	V_{DD} value for LVD trip					
V_{LVD0}	VM[2:0] = 000b	2.40	2.45	2.51[21]	V	
V_{LVD1}	VM[2:0] = 001b	2.85	2.92	2.99[22]	V	
V_{LVD2}	VM[2:0] = 010b	2.95	3.02	3.09	V	
V_{LVD3}	VM[2:0] = 011b	3.06	3.13	3.20	V	
V_{LVD4}	VM[2:0] = 100b	4.37	4.48	4.55	V	
V_{LVD5}	VM[2:0] = 101b	4.50	4.64	4.75	V	
V_{LVD6}	VM[2:0] = 110b	4.62	4.73	4.83	V	
V_{LVD7}	VM[2:0] = 111b	4.71	4.81	4.95	V	
	V_{DD} value for pump trip					
V_{PUMP0}	VM[2:0] = 000b	2.45	2.55	2.62[23]	V	
V_{PUMP1}	VM[2:0] = 001b	2.96	3.02	3.09	V	
V_{PUMP2}	VM[2:0] = 010b	3.03	3.10	3.16	V	
V_{PUMP3}	VM[2:0] = 011b	3.18	3.25	3.32[24]	V	
V_{PUMP4}	VM[2:0] = 100b	4.54	4.64	4.74	V	
V_{PUMP5}	VM[2:0] = 101b	4.62	4.73	4.83	V	
V_{PUMP6}	VM[2:0] = 110b	4.71	4.82	4.92	V	
V_{PUMP7}	VM[2:0] = 111b	4.89	5.00	5.12	V	

Notes
21. Always greater than 50 mV above V_{PPOR} (PORLEV = 00) for falling supply.
22. Always greater than 50 mV above V_{PPOR} (PORLEV = 01) for falling supply.
23. Always greater than 50 mV above V_{LVD0}.
24. Always greater than 50 mV above V_{LVD3}.

DC Programming Specifications

Table 14 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 14. DC Programming Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
V_{DDP}	V_{DD} for programming and erase	4.5	5	5.5	V	This specification applies to the functional requirements of external programmer tools
V_{DDLV}	Low V_{DD} for verify	2.4	2.5	2.6	V	This specification applies to the functional requirements of external programmer tools
V_{DDHV}	High V_{DD} for verify	5.1	5.2	5.3	V	This specification applies to the functional requirements of external programmer tools
$V_{DDIWRITE}$	Supply voltage for flash write operation	2.7		5.25	V	This specification applies to this device when it is executing internal flash writes
I_{DDP}	Supply current during programming or verify	–	5	25	mA	
V_{ILP}	Input low voltage during programming or verify	–	–	0.8	V	
V_{IHP}	Input high voltage during programming or verify	2.2	–	–	V	
I_{ILP}	Input current when applying V_{ILP} to P1[0] or P1[1] during programming or verify	–	–	0.2	mA	Driving internal pull-down resistor
I_{IHP}	Input current when applying V_{IHP} to P1[0] or P1[1] during programming or verify	–	–	1.5	mA	Driving internal pull-down resistor
V_{OLV}	Output low voltage during programming or verify	–	–	V_{SS} + 0.75	V	
V_{OHV}	Output high voltage during programming or verify	V_{DD} – 1.0	–	V_{DD}	V	
$Flash_{ENPB}$	Flash endurance (per block)	50,000[25]	–	–	–	Erase/write cycles per block
$Flash_{ENT}$	Flash endurance (total)[26]	1,800,000	–	–	–	Erase/write cycles
$Flash_{DR}$	Flash data retention	10	–	–	Years	

DC I^2C Specifications

Table 15 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤T_A ≤85 °C, 3.0 V to 3.6 V and –40 °C ≤T_A ≤85 °C, or 2.4 V to 3.0 V and –40 °C ≤T_A ≤85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 15. DC I^2C Specifications[27]

Symbol	Description	Min	Typ	Max	Units	Notes
V_{ILI2C}	Input low level	–	–	0.3 × V_{DD}	V	2.4 V ≤ V_{DD} ≤ 3.6 V
		–	–	0.25 × V_{DD}	V	4.75 V ≤ V_{DD} ≤ 5.25 V
V_{IHI2C}	Input high level	0.7 × V_{DD}	–	–	V	2.4 V ≤ V_{DD} ≤ 5.25 V

Notes

25. The 50,000 cycle flash endurance per block is only guaranteed if the flash is operating within one voltage range. Voltage ranges are 2.4 V to 3.0 V, 3.0 V to 3.6 V, and 4.75 V to 5.25 V.
26. A maximum of 36 × 50,000 block endurance cycles is allowed. This may be balanced between operations on 36 × 1 blocks of 50,000 maximum cycles each, 36×2 blocks of 25,000 maximum cycles each, or 36 × 4 blocks of 12,500 maximum cycles each (to limit the total number of cycles to 36 × 50,000 and ensure that no single block ever sees more than 50,000 cycles). For the full industrial range, you must employ a temperature sensor user module (FlashTemp) and feed the result to the temperature argument before writing. Refer to the Flash APIs application note AN2015 (Design Aids - Reading and Writing PSoC® Flash) for more information.
27. All GPIO meet the DC GPIO VIL and VIH specifications found in the DC GPIO Specifications sections. The I^2C GPIO pins also meet the above specs.

Table 17. 2.7-V AC Chip-Level Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
F_{IMO12} [33]	IMO frequency for 12 MHz	11.04	12	12.96 [34, 35]	MHz	Trimmed for 2.7 V operation using factory trim values. See Figure 14 on page 20. SLIMO mode = 1
F_{IMO6} [33]	IMO frequency for 6 MHz	5.52	6	6.48 [34, 35]	MHz	Trimmed for 2.7 V operation using factory trim values. See Figure 14 on page 20. SLIMO mode = 1
F_{CPU1}	CPU frequency (2.7 V nominal)	0.093	3	3.15[34]	MHz	12 MHz only for SLIMO mode = 0
F_{BLK27}	Digital PSoC block frequency (2.7 V nominal)	0	12	12.5[34,35]	MHz	Refer to AC Digital Block Specifications on page 29
F_{32K1}	ILO frequency	8	32	96	kHz	
F_{32K_U}	ILO untrimmed frequency	5	–	100	kHz	After a reset and before the M8C starts to run, the ILO is not trimmed. See the System Resets section of the *PSoC Technical Reference Manual* for details on this timing
t_{XRST}	External reset pulse width	10	–	–	µs	
DC_{ILO}	IILO duty cycle	20	50	80	%	
F_{MAX}	Maximum frequency of signal on row input or row output.	–	–	12.3	MHz	
SR_{POWER_UP}	Power supply slew rate	–	–	250	V/ms	V_{DD} slew rate during power-up
$t_{POWERUP}$	Time from end of POR to CPU executing code	–	16	100	ms	Power-up from 0 V. See the System Resets section of the *PSoC Technical Reference Manual*.
t_{jit_IMO}	12 MHz IMO cycle-to-cycle jitter (RMS)[36]	–	400	1000	ps	
	12 MHz IMO long term N cycle-to-cycle jitter (RMS)[36]	–	600	1300	ps	N = 32
	12 MHz IMO period jitter (RMS)[36]	–	100	500	ps	

Notes
33. Errata: The worst case IMO frequency deviation when operated below 0 °C and above +70 °C and within the upper and lower datasheet temperature range is ±5%.
34. 2.4 V < V_{DD} < 3.0 V.
35. See Application Note AN2012 “Adjusting PSoC Microcontroller Trims for Dual Voltage-Range Operation” available at http://www.cypress.com for information on maximum frequency for user modules.
36. Refer to Cypress Jitter Specifications Application Note AN5054 “Understanding Datasheet Jitter Specifications for Cypress Timing Products” at www.cypress.com under Application Notes for more information.

AC Digital Block Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 21. 5-V and 3.3-V AC Digital Block Specifications

Function	Description	Min	Typ	Max	Unit	Notes
All functions	Block input clock frequency					
	V_{DD} ≥ 4.75 V	–	–	49.2	MHz	
	V_{DD} < 4.75 V	–	–	24.6	MHz	
Timer	Input clock frequency					
	No capture, V_{DD} ≥ 4.75 V	–	–	49.2	MHz	
	No capture, V_{DD} < 4.75 V	–	–	24.6	MHz	
	With capture	–	–	24.6	MHz	
	Capture pulse width	50[37]	–	–	ns	
Counter	Input clock frequency					
	No enable input, V_{DD} ≥ 4.75 V	–	–	49.2	MHz	
	No enable input, V_{DD} < 4.75 V	–	–	24.6	MHz	
	With enable input	–	–	24.6	MHz	
	Enable input pulse width	50[37]	–	–	ns	
Dead Band	Kill pulse width					
	Asynchronous restart mode	20	–	–	ns	
	Synchronous restart mode	50[37]	–	–	ns	
	Disable mode	50[37]	–	–	ns	
	Input clock frequency					
	V_{DD} ≥ 4.75 V	–	–	49.2	MHz	
	V_{DD} < 4.75 V	–	–	24.6	MHz	
CRCPRS (PRS Mode)	Input clock frequency					
	V_{DD} ≥ 4.75 V	–	–	49.2	MHz	
	V_{DD} < 4.75 V	–	–	24.6	MHz	
CRCPRS (CRC Mode)	Input clock frequency	–	–	24.6	MHz	
SPIM	Input clock frequency	–	–	8.2	MHz	The SPI serial clock (SCLK) frequency is equal to the input clock frequency divided by 2.
SPIS	Input clock (SCLK) frequency	–	–	4.1	MHz	The input clock is the SPI SCLK in SPIS mode.
	Width of SS_negated between transmissions	50[37]	–	–	ns	
Transmitter	Input clock frequency					The baud rate is equal to the input clock frequency divided by 8.
	V_{DD} ≥ 4.75 V, 2 stop bits	–	–	49.2	MHz	
	V_{DD} ≥ 4.75 V, 1 stop bit	–	–	24.6	MHz	
	V_{DD} < 4.75 V	–	–	24.6	MHz	
Receiver	Input clock frequency					The baud rate is equal to the input clock frequency divided by 8.
	V_{DD} ≥ 4.75 V, 2 stop bits	–	–	49.2	MHz	
	V_{DD} ≥ 4.75 V, 1 stop bit	–	–	24.6	MHz	
	V_{DD} < 4.75 V	–	–	24.6	MHz	

Note
37. 50 ns minimum input pulse width is based on the input synchronizers running at 24 MHz (42 ns nominal period).

AC Programming Specifications

Table 26 lists the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, or 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 26. AC Programming Specifications

Symbol	Description	Min	Typ	Max	Units	Notes
T_{RSCLK}	Rise time of SCLK	1	–	20	ns	
T_{FSCLK}	Fall time of SCLK	1	–	20	ns	
T_{SSCLK}	Data setup time to falling edge of SCLK	40	–	–	ns	
T_{HSCLK}	Data hold time from falling edge of SCLK	40	–	–	ns	
F_{SCLK}	Frequency of SCLK	0	–	8	MHz	
T_{ERASEB}	Flash erase time (block)	–	10	–	ms	
T_{WRITE}	Flash block write time	–	40	–	ms	
T_{DSCLK}	Data out delay from falling edge of SCLK	–	–	45	ns	3.6 < V_{DD}
T_{DSCLK3}	Data out delay from falling edge of SCLK	–	–	50	ns	3.0 ≤ V_{DD} ≤ 3.6
T_{DSCLK2}	Data out delay from falling edge of SCLK	–	–	70	ns	2.4 ≤ V_{DD} ≤ 3.0
$T_{ERASEALL}$	Flash erase time (Bulk)	–	20	–	ms	Erase all blocks and protection fields at once
$T_{PROGRAM\_HOT}$	Flash block erase + flash block write time	–	–	100[39]	ms	0 °C ≤ Tj ≤ 100 °C
$T_{PROGRAM\_COLD}$	Flash block erase + flash block write time	–	–	200[39]	ms	–40 °C ≤ Tj ≤ 0 °C

AC I^2C [40] Specifications

The following tables list the guaranteed maximum and minimum specifications for the voltage and temperature ranges: 4.75 V to 5.25 V and –40 °C ≤ T_A ≤ 85 °C, 3.0 V to 3.6 V and –40 °C ≤ T_A ≤ 85 °C, or 2.4 V to 3.0 V and –40 °C ≤ T_A ≤ 85 °C, respectively. Typical parameters are measured at 5 V, 3.3 V, or 2.7 V at 25 °C and are for design guidance only.

Table 27. AC Characteristics of the I^2C SDA and SCL Pins for V_{DD} ≥ 3.0 V

Symbol	Description	Standard Mode		Fast Mode		Units
		Min	Max	Min	Max	
F_{SCLI2C}	SCL clock frequency	0	100	0	400	kHz
$T_{HDSTAI2C}$	Hold time (repeated) start condition. After this period, the first clock pulse is generated	4.0	–	0.6	–	µs
T_{LOWI2C}	Low period of the SCL clock	4.7	–	1.3	–	µs
$T_{HIGHI2C}$	High period of the SCL clock	4.0	–	0.6	–	µs
$T_{SUSTAI2C}$	Setup time for a repeated start condition	4.7	–	0.6	–	µs
$T_{HDDATI2C}$	Data hold time	0	–	0	–	µs
$T_{SUDATI2C}$	Data setup time	250	–	100[41]	–	ns
$T_{SUSTOI2C}$	Setup time for stop condition	4.0	–	0.6	–	µs
T_{BUFI2C}	Bus free time between a stop and start condition	4.7	–	1.3	–	µs
T_{SPI2C}	Pulse width of spikes suppressed by the input filter.	–	–	0	50	ns

Notes

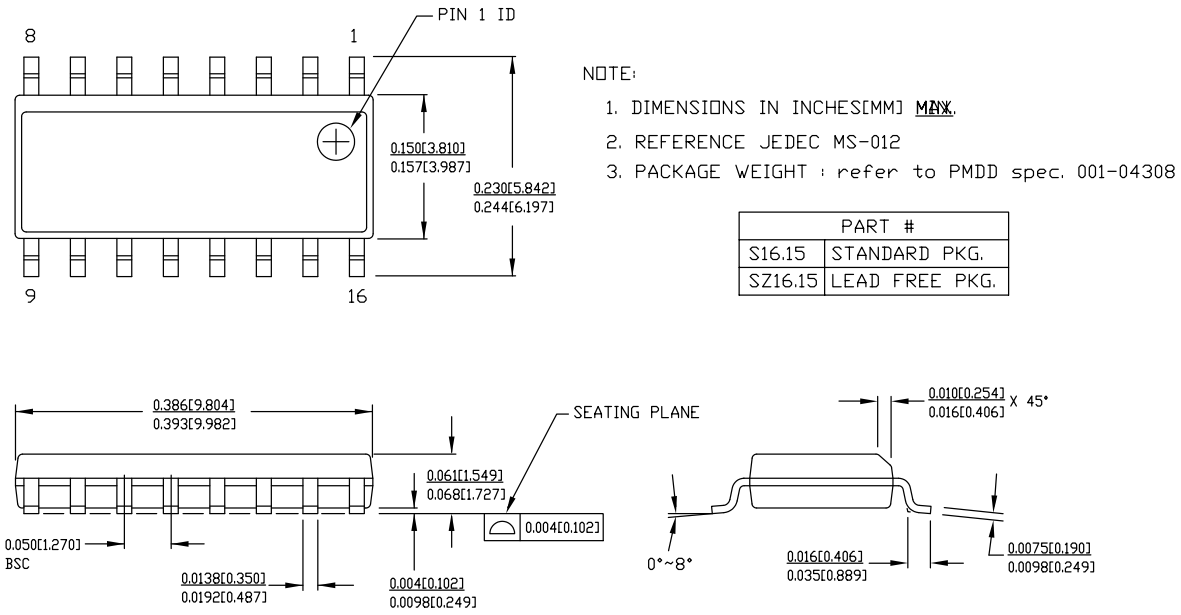
39. For the full industrial range, the user must employ a temperature sensor user module (FlashTemp) and feed the result to the temperature argument before writing. Refer to the Flash APIs application note AN2015 (Design Aids - Reading and Writing PSoC® Flash) for more information.
40. Errata: The I^2C block exhibits occasional data and bus corruption errors when the I^2C master initiates transactions while the device is transitioning in to or out of sleep mode.
41. A Fast-Mode I^2C-bus device may be used in a Standard-Mode I^2C-bus system, but it must meet the requirement $T_{SU;DAT}$ ≥ 250 ns. This is automatically the case if the device does not stretch the LOW period of the SCL signal. If the device does stretch the LOW period of the SCL signal, it must output the next data bit to the SDA line T_{rmax} + $T_{SU;DAT}$ = 1000 + 250 = 1250 ns (according to the Standard-Mode I^2C-bus specification) before the SCL line is released.

Packaging Information

This section shows the packaging specifications for the CY8C21x34 PSoC device with the thermal impedances for each package.

Important Note Emulation tools may require a larger area on the target PCB than the chip's footprint. For a detailed description of the emulation tools' dimensions, refer to the emulator pod drawings at http://www.cypress.com.

Figure 15. 16-pin SOIC (150 Mils) Package Outline, 51-85068



51-85068 *E

Figure 16. 20-pin SSOP (210 Mils) Package Outline, 51-85077

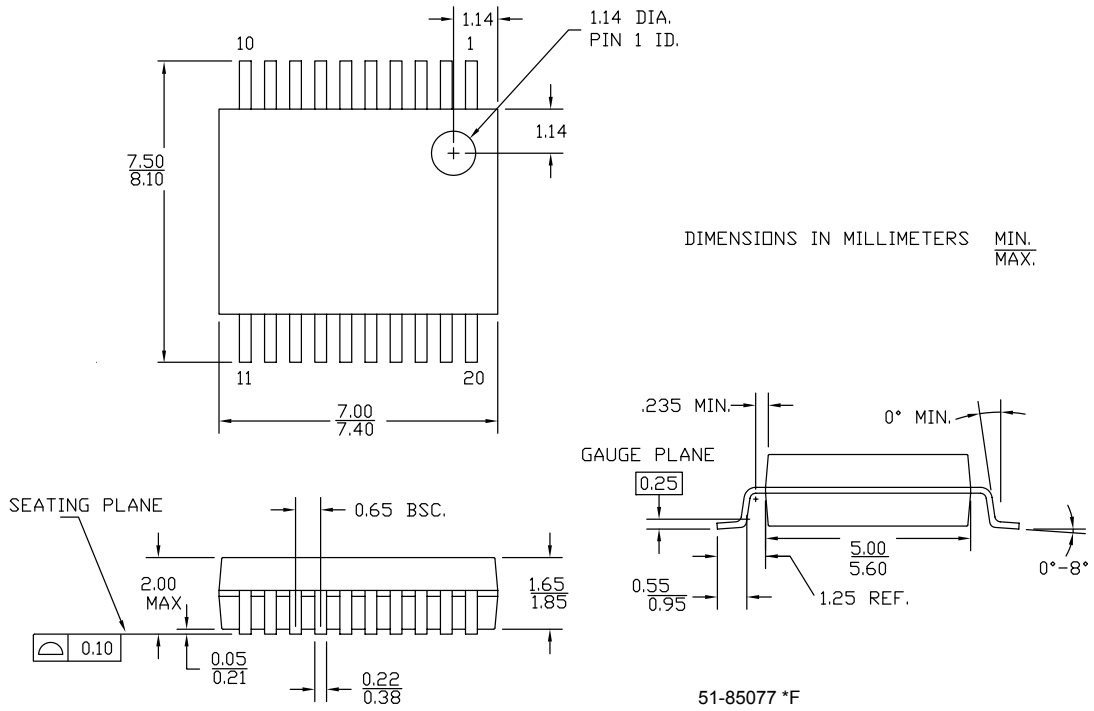


Figure 17. 28-pin SSOP (210 Mils) Package Outline, 51-85079

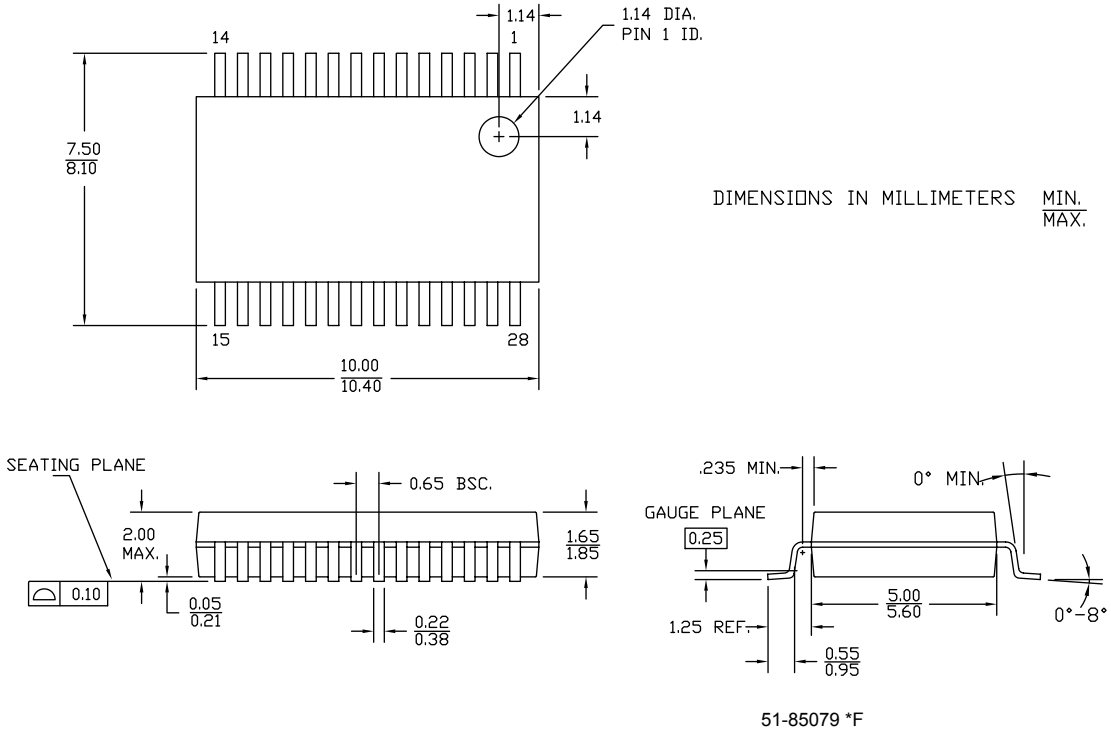
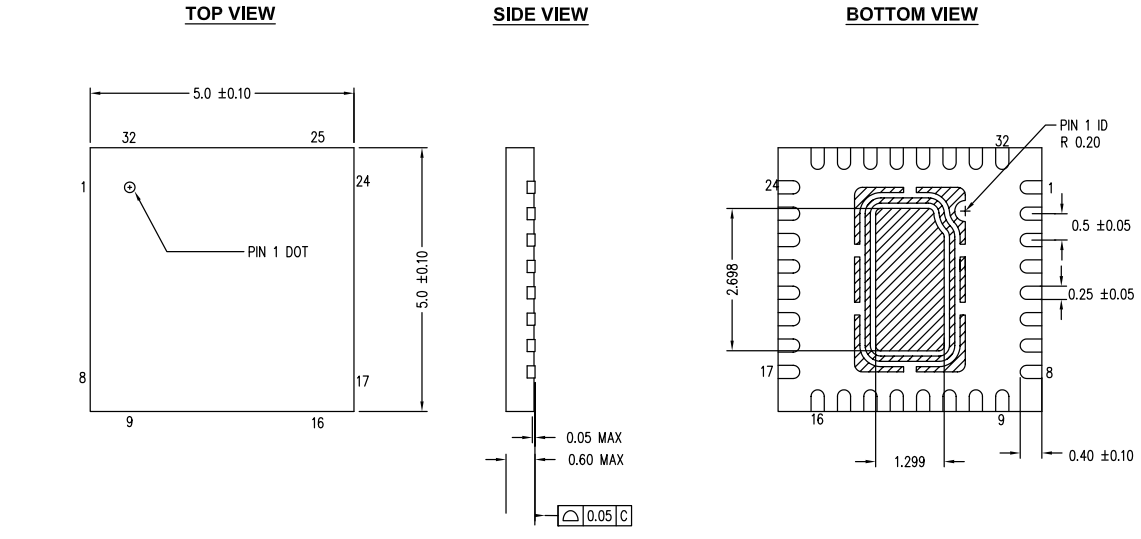


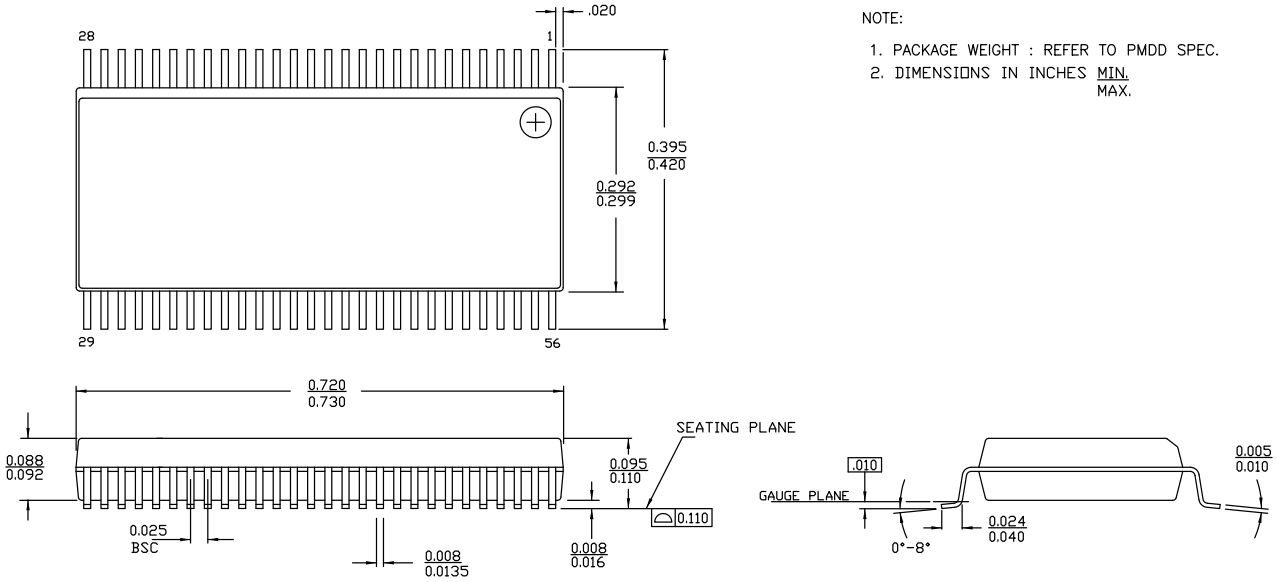
Figure 19. 32-pin QFN (5 × 5 × 0.55 mm) LQ32A 1.3 × 2.7 E-Pad (Sawn Type) Package Outline, 001-48913



NOTES:
1. HATCH AREA IS SOLDERABLE EXPOSED PAD
2. BASED ON REF JEDEC # MO-248
3. PACKAGE WEIGHT: 38mg ± 4 mg
4. ALL DIMENSIONS ARE IN MILLIMETERS

001-48913 *D

Figure 20. 56-pin SSOP (300 Mils) Package Outline, 51-85062



NOTE:
1. PACKAGE WEIGHT : REFER TO PMDD SPEC.
2. DIMENSIONS IN INCHES MIN.
MAX.

51-85062 *F

Thermal Impedances

Table 29. Thermal Impedances per Package

Package	Typical θ_{JA} [42]	Typical θ_{JC}
16-pin SOIC	123 °C/W	55 °C/W
20-pin SSOP	117 °C/W	41 °C/W
28-pin SSOP	96 °C/W	39 °C/W
32-pin QFN[43] 5 × 5 mm 0.60 Max	27 °C/W	15 °C/W
32-pin QFN[43] 5 × 5 mm 1.00 Max	22 °C/W	12 °C/W
56-pin SSOP	48 °C/W	24 °C/W

Solder Reflow Specifications

Table 30 shows the solder reflow temperature limits that must not be exceeded.

Table 30. Solder Reflow Specifications

Package	Maximum Peak Temperature (T_C)	Maximum Time above T_C – 5 °C
16-pin SOIC	260 °C	30 seconds
20-pin SSOP	260 °C	30 seconds
28-pin SSOP	260 °C	30 seconds
32-pin QFN	260 °C	30 seconds
56-pin SSOP	260 °C	30 seconds

Notes
42. $T_J = T_A + \text{Power} \times \theta_{JA}$
43. To achieve the thermal impedance specified for the QFN package, refer to *Application Note EROS - Design Guidelines for Cypress Quad Flat No Extended Lead (QFN) Packaged Devices* available at http://www.cypress.com.
44. Higher temperatures may be required based on the solder melting point. Typical temperatures for solder are 220 ± 5 °C with Sn-Pb or 245 ± 5 °C with Sn-Ag-Cu paste. Refer to the solder manufacturer specifications.

Acronyms

Table 32 lists the acronyms that are used in this document.

Table 32. Acronyms Used in this Datasheet

Acronym	Description	Acronym	Description
AC	alternating current	MIPS	million instructions per second
ADC	analog-to-digital converter	OCD	on-chip debug
API	application programming interface	PCB	printed circuit board
CMOS	complementary metal oxide semiconductor	PDIP	plastic dual-in-line package
CPU	central processing unit	PGA	programmable gain amplifier
CRC	cyclic redundancy check	PLL	phase-locked loop
CT	continuous time	POR	power on reset
DAC	digital-to-analog converter	PPOR	precision power on reset
DC	direct current	PRS	pseudo-random sequence
DTMF	dual-tone multi-frequency	PSoC®	Programmable System-on-Chip
ECO	external crystal oscillator	PWM	pulse width modulator
EEPROM	electrically erasable programmable read-only memory	QFN	quad flat no leads
GPIO	general purpose I/O	RTC	real time clock
ICE	in-circuit emulator	SAR	successive approximation
IDE	integrated development environment	SC	switched capacitor
ILO	internal low speed oscillator	SLIMO	slow IMO
IMO	internal main oscillator	SMP	switch-mode pump
I/O	input/output	SOIC	small-outline integrated circuit
IrDA	infrared data association	SPI™	serial peripheral interface
ISSP	in-system serial programming	SRAM	static random access memory
LCD	liquid crystal display	SROM	supervisory read only memory
LED	light-emitting diode	SSOP	shrink small-outline package
LPC	low power comparator	UART	universal asynchronous receiver / transmitter
LVD	low voltage detect	USB	universal serial bus
MAC	multiply-accumulate	WDT	watchdog timer
MCU	microcontroller unit	XRES	external reset

Reference Documents

CY8CPLC20, CY8CLED16P01, CY8C29x66, CY8C27x43, CY8C24x94, CY8C24x23, CY8C24x23A, CY8C22x13, CY8C21x34, CY8C21x23, CY7C64215, CY7C603xx, CY8CNP1xx, and CYWUSB6953 PSoC® Programmable System-on-Chip Technical Reference Manual (TRM) (001-14463)

Design Aids – Reading and Writing PSoC® Flash - AN2015 (001-40459)

Application Notes for Surface Mount Assembly of Amkor's MicroLeadFrame (MLF) Packages – available at http://www.amkor.com.

Document Conventions

Units of Measure

Table 33 lists the units of measures.

Table 33. Units of Measure

Symbol	Unit of Measure	Symbol	Unit of Measure
kB	1024 bytes	µH	micro henry
dB	decibels	µs	microsecond
°C	degree Celsius	ms	millisecond
µF	microfarad	ns	nanosecond
fF	femto farad	ps	picosecond
pF	picofarad	µV	microvolt
kHz	kilohertz	mV	millivolts
MHz	megahertz	mVpp	millivolts peak-to-peak
rt-Hz	root hertz	nV	nano volt
kΩ	kilo ohm	V	volt
Ω	ohm	µW	microwatt
µA	microampere	W	watt
mA	milliampere	mm	millimeter
nA	nano ampere	ppm	parts per million
pA	pico ampere	%	percent
mH	millihenry		

Numeric Conventions

Hexadecimal numbers are represented with all letters in uppercase with an appended lowercase ‘h’ (for example, ‘14h’ or ‘3Ah’). Hexadecimal numbers may also be represented by a ‘0x’ prefix, the C coding convention. Binary numbers have an appended lowercase ‘b’ (for example, 01010100b’ or ‘01000011b’). Numbers not indicated by an ‘h’ or ‘b’ are decimals.

Glossary

active high	1. A logic signal having its asserted state as the logic 1 state. 2. A logic signal having the logic 1 state as the higher voltage of the two states.
analog blocks	The basic programmable opamp circuits. These are SC (switched capacitor) and CT (continuous time) blocks. These blocks can be interconnected to provide ADCs, DACs, multi-pole filters, gain stages, and much more.
analog-to-digital (ADC)	A device that changes an analog signal to a digital signal of corresponding magnitude. Typically, an ADC converts a voltage to a digital number. The digital-to-analog (DAC) converter performs the reverse operation.
Application programming interface (API)	A series of software routines that comprise an interface between a computer application and lower level services and functions (for example, user modules and libraries). APIs serve as building blocks for programmers that create software applications.
asynchronous	A signal whose data is acknowledged or acted upon immediately, irrespective of any clock signal.
bandgap reference	A stable voltage reference design that matches the positive temperature coefficient of VT with the negative temperature coefficient of VBE, to produce a zero temperature coefficient (ideally) reference.
bandwidth	1. The frequency range of a message or information processing system measured in hertz. 2. The width of the spectral region over which an amplifier (or absorber) has substantial gain (or loss); it is sometimes represented more specifically as, for example, full width at half maximum.

Errata

This section describes the errata for the PSoC® Programmable System-on-Chip CY8C21X34. Details include errata trigger conditions, scope of impact, available workarounds, and silicon revision applicability.

Contact your local Cypress Sales Representative if you have questions.

Part Numbers Affected

Part Number	Ordering Information
CY8C21X34	CY8C21234-24SXI
	CY8C21234-24SXIT
	CY8C21334-24PVXI
	CY8C21334-24PVXIT
	CY8C21534-24PVXI
	CY8C21534-24PVXIT
	CY8C21434-24LFXI
	CY8C21434-24LFXIT
	CY8C21434-24LKXI
	CY8C21434-24LKXIT
	CY8C21634-24LFXI
	CY8C21634-24LFXIT
	CY8C21434-24LTXI
	CY8C21434-24LTXIT
	CY8C21434-24LQXI
	CY8C21434-24LQXIT
	CY8C21634-24LTXI
	CY8C21634-24LTXIT
	CY8C21001-24PVXI

CY8C21X34 Qualification Status

Product Status: Production

CY8C21X34 Errata Summary

The following table defines the errata applicability to available CY8C21X34 family devices. An "X" indicates that the errata pertains to the selected device.

Note Errata items, in the table below, are hyperlinked. Click on any item entry to jump to its description.

Items	Part Number	Silicon Revision	Fix Status
[1.]. Internal Main Oscillator (IMO) Tolerance Deviation at Temperature Extremes	CY8C21X34	A	No fix is currently planned.
[2]. I2C Errors	CY8C21X34	A	No fix is currently planned.

1. Internal Main Oscillator (IMO) Tolerance Deviation at Temperature Extremes

- **Problem Definition**
  Asynchronous Digital Communications Interfaces may fail framing beyond 0 °C to 70 °C. This problem does not affect end-product usage between 0 °C and 70 °C.
- **Parameters Affected**
  The IMO frequency tolerance. The worst case deviation when operated below 0 °C and above +70 °C and within the upper and lower datasheet temperature range is ±5%.
- **Trigger Condition(S)**
  The asynchronous Rx/Tx clock source IMO frequency tolerance may deviate beyond the datasheet limit of ±2.5% when operated beyond the temperature range of 0 °C to +70 °C.
- **Scope of Impact**
  This problem may affect UART, IrDA, and FSK implementations.
- **Workaround**
  Implement a quartz crystal stabilized clock source on at least one end of the asynchronous digital communications interface.
- **Fix Status**
  No fix is currently planned.

2. I^2C Errors

- **Problem Definition**
  The I^2C block exhibits occasional data and bus corruption errors when the I^2C master initiates transactions while the device is transitioning in to or out of sleep mode.
- **Parameters Affected**
  Affects reliability of I^2C communication to device, between I^2C master, and third party I^2C slaves.
- **Trigger Condition(S)**
  Triggered by transitions into and out of the device's sleep mode.
- **Scope of Impact**
  This problem may affect UART, IrDA, and FSK implementations.
- **Workaround**
  Firmware workarounds are available in firmware. Generally the workaround consists of disconnecting the I^2C block from the bus prior to going to sleep modes. I^2C transactions during sleep are supported by a protocol in which the master wakes the device prior to the I^2C transaction
- **Fix Status**
  Will not be fixed.

Document History Page (continued)

Document Title: CY8C21634/CY8C21534/CY8C21434/CY8C21334/CY8C21234, PSoC® Programmable System-on-Chip™ Document Number: 38-12025				
Rev.	**ECN**	**Orig. of Change**	**Submission Date**	**Description of Change**
*Z	3902039	VNJ	02/12/2013	Updated Electrical Specifications (Updated AC Electrical Characteristics (Updated AC Chip-Level Specifications (Updated Table 16 (Changed minimum value of F_{IMO6} parameter from 5.5 MHz to 5.52 MHz, changed maximum value of F_{IMO6} parameter from 6.5 MHz to 6.48 MHz), updated Table 17 (Changed minimum value of F_{IMO12} parameter from 11.5 MHz to 11.04 MHz, changed maximum value of F_{IMO12} parameter from 12.7 MHz to 12.96 MHz, changed minimum value of F_{IMO6} parameter from 5.5 MHz to 5.52 MHz, changed maximum value of F_{IMO6} parameter from 6.5 MHz to 6.48 MHz)))). Updated Packaging Information: spec 51-85068 – Changed revision from *D to *E. spec 001-30999 – Changed revision from *C to *D. spec 001-48913 – Changed revision from *B to *C. spec 51-85062 – Changed revision from *E to *F.
AA	3993249	SLAN	05/07/2013	Added Errata.
AB	4076892	SLAN	07/25/2013	Added Errata footnotes (Notes 1, 2, 3, 4, 5, 8, 28, 33, 40). Updated Features: Added Note 1 and referred in “Internal ±2.5% 24- / 48-MHz main oscillator”. Added Note 2 and referred in “I^2C” under “Additional system resources”. Updated PSoC Functional Overview: Updated The PSoC Core: Added Note 3 and referred in “24 MHz”. Added Note 4 and referred in “I^2C” under “System resources provide these additional capabilities”. Updated The Digital System: Added Note 4 and referred in “I^2C slave and multi-master”. Updated Additional System Resources: Added Note 5 and referred in “I^2C”. Updated Development Tools: Added Note 8 and referred in “I^2C” under “Built-in support for communication interfaces”. Updated Electrical Specifications: Updated AC Electrical Characteristics: Updated AC Chip-Level Specifications: Added Note 28 and referred in “F_{IMO24}” and “F_{IMO6}” parameters in Table 16. Added Note 33 and referred in “F_{IMO12}” and “F_{IMO6}” parameters in Table 17. Updated AC I2C [40] Specifications: Added Note 40 and referred in the heading. Updated to new template. Completing Sunset Review.
AC	4143112	DCHE	10/01/2013	Updated Packaging Information: spec 001-48913 – Changed revision from *C to *D. Updated Ordering Information (Updated part numbers). Updated Reference Documents: Removed references of spec 001-14503 and spec 001-17397 as these specs are obsolete.

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